

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF85A W2 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2004-9-26 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



# 1. SCOPE

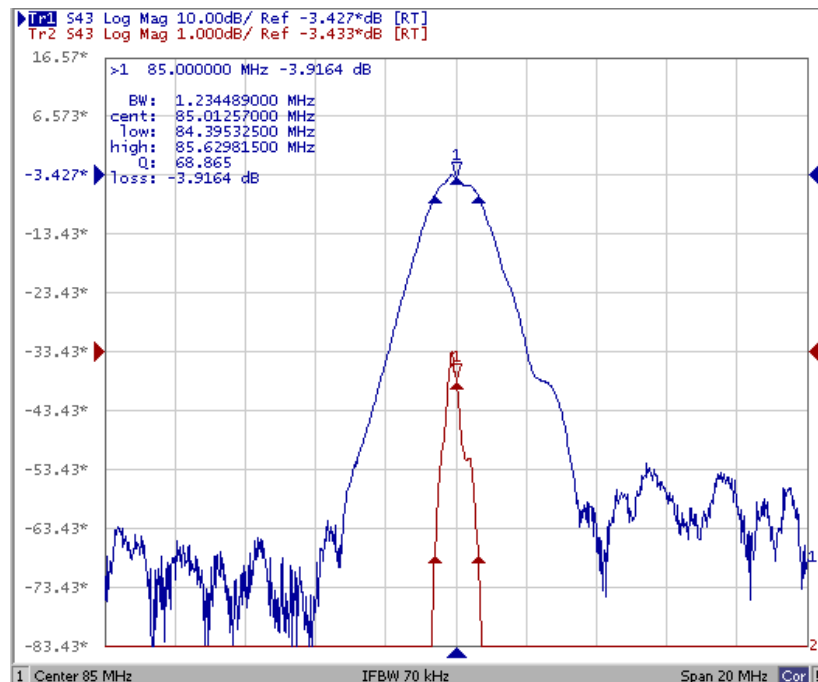
This specification shall cover the characteristics of SAW filter F85A

# 2. ELECTRICAL SPECIFICATION

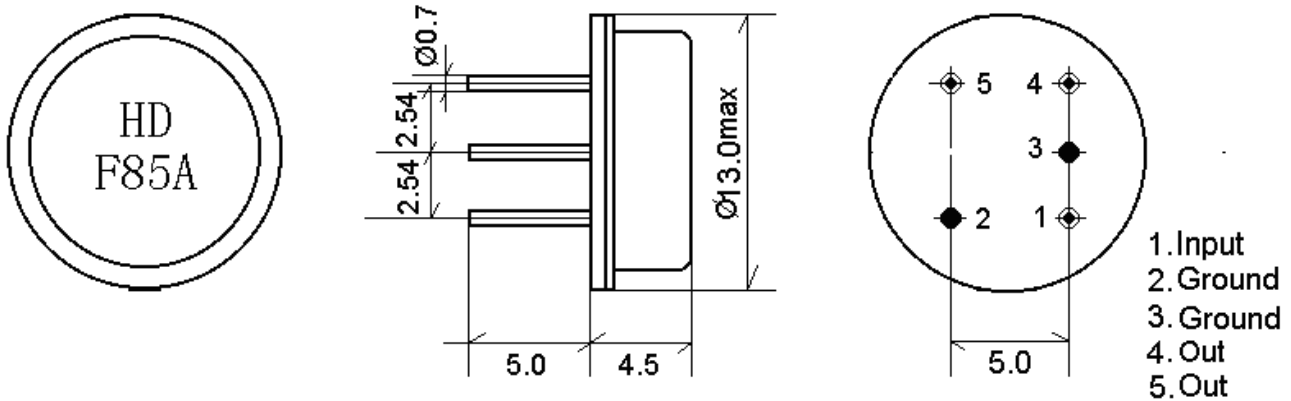
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

## 2.2 Electronic Characteristics

型号 Part Number	HDF85A
中心频率(fo)(MHz) Nominal Center Frequency	85.0
3dB 带宽 Bandwidth(from fo)(MHz)	1.5 typ.
30dB 带宽 Bandwidth(from fo)(MHz)	4.5Mhzmax.
插入损耗(dB) Insertion Loss(at minimum loss point)	6.0max
群延时波动(fo+/-576KHz)(μ sce.) Group Delay Deviation	0.200
输入/输出阻抗 Input/output Impedance	50 Ω //0pF



### 3. DIMENSION



### 4. ENVIRONMENTAL CHARACTERISTICS

#### 4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

#### 4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

#### 4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

#### 4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

#### 4-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

#### 4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

#### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

### 6. REMARK

**6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

**6.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

**6.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.